



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



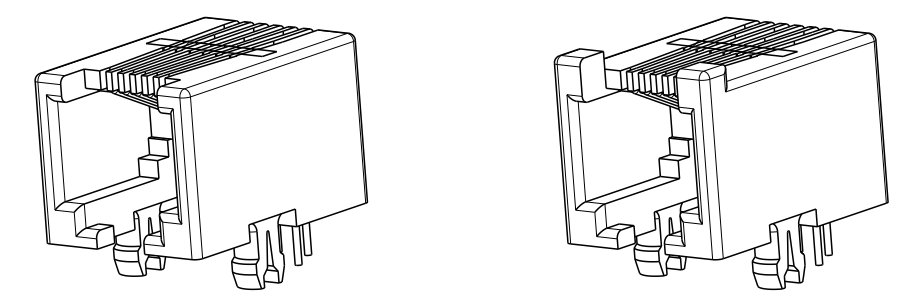
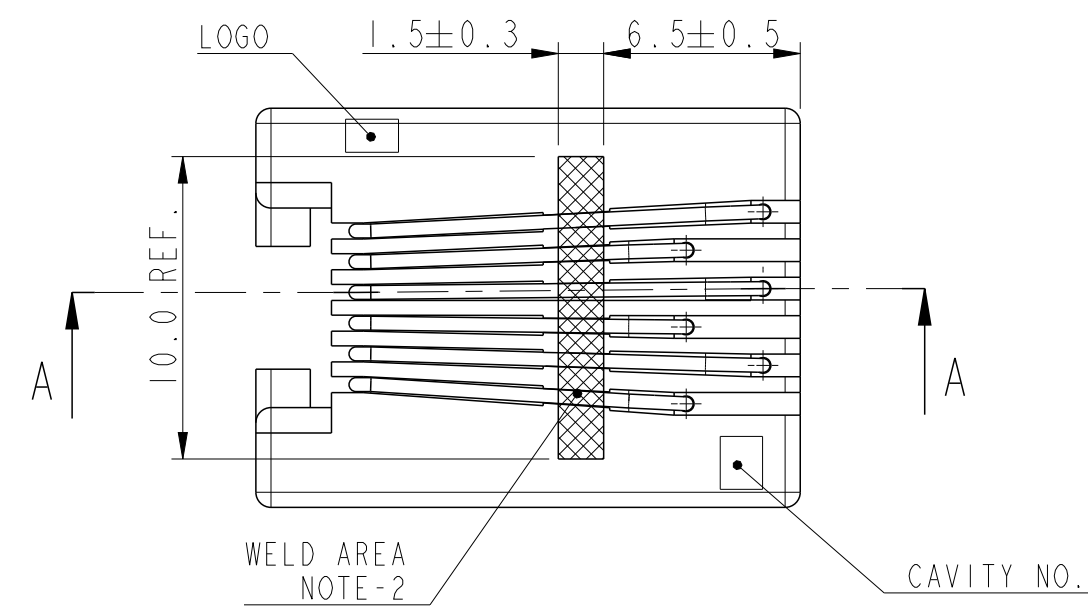
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





PRODUCT NO. 54601 X 06 XXX WP LF

TELEJACK PCB SERIES

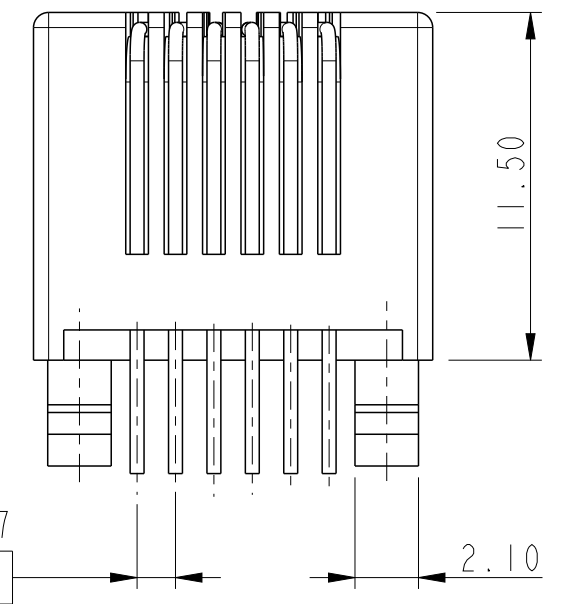
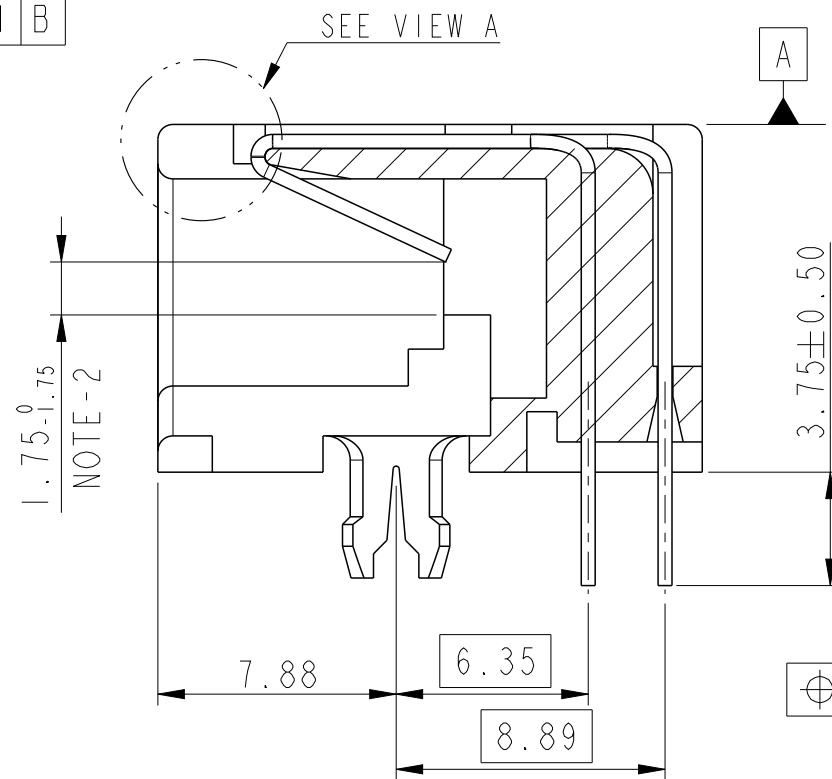
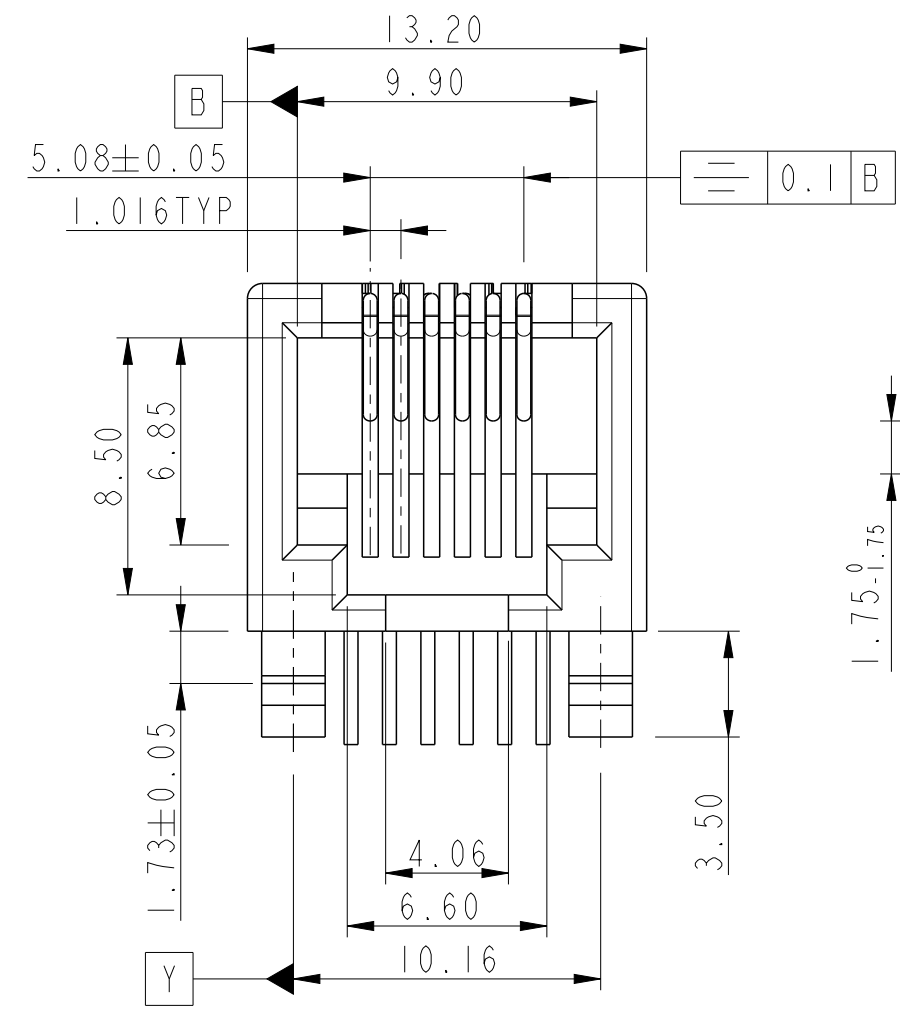
LEAD FREE

PLATING
 2-0.08μ Au SELECTIVE MIN.
 6-0.8μ Au SELECTIVE MIN.
 7-Au FLASH SELECTIVE MIN.
 8-1.27μ Au SELECTIVE MIN.
 9-0.38μ Au SELECTIVE MIN.

*SPECIAL CODE
 WP-WITHOUT PROJECTION
 BLANK-WITH PROJECTION

NO. OF POS
 06-6 POL INSULATOR

CONTACTS LOADED
 BLANK-CTS. LOADED IN ALL POS.
 001-CTS. LOADED IN 3&4 POS.
 002-CTS. LOADED IN 2,3,4&5 POS.



SECTION A-A
 SCALE 4:1

TECHNICAL SPECIFICATION:

Insulation Resistance - 500 M Ohms min.
 Dielectric Strength - 1000 V rms, 60 Hz.
 Contact Resistance - 20 to 30 m Ohms. max.
 Current Rating - 2.0 amp DC
 Maximum Total Mating Force - 20 N
 Retention Force Between Plug & Jack-22.5 N min.
 Durability - 250 mating cycles

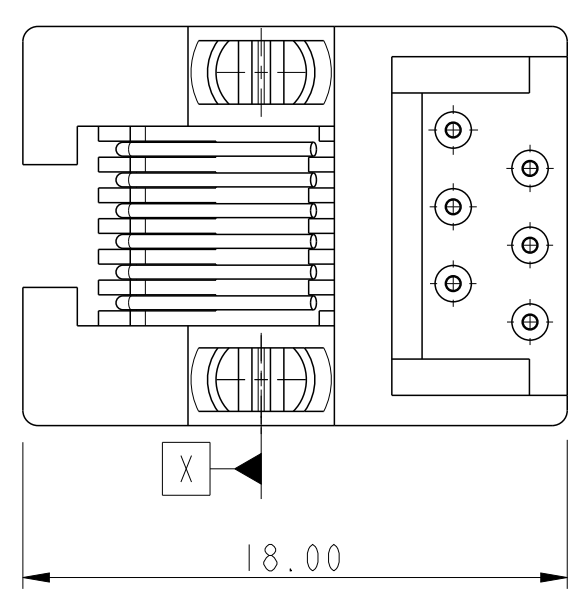
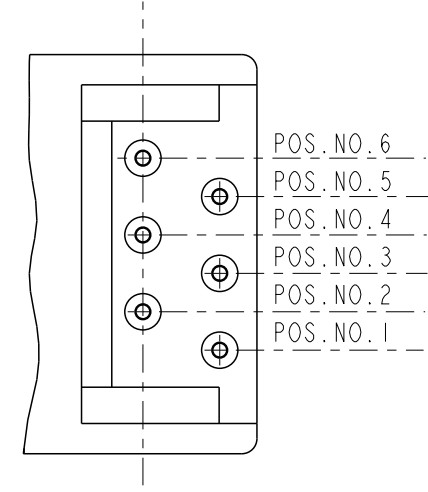
MATERIAL
 Housing: THERMOPLASTIC-UL94 V0 BLACK
 Contact: Ø0.46 COPPER ALLOY ROUND WIRE

Material:
 The housing will withstand exposure to 260-265°C for 5 seconds in a wavesoldering application. Use protective adhesive tape (Kapton or Teflon) or protective metallic devices on the areas which are directly exposed to wave soldering as it is used in classical leaded wave soldering.

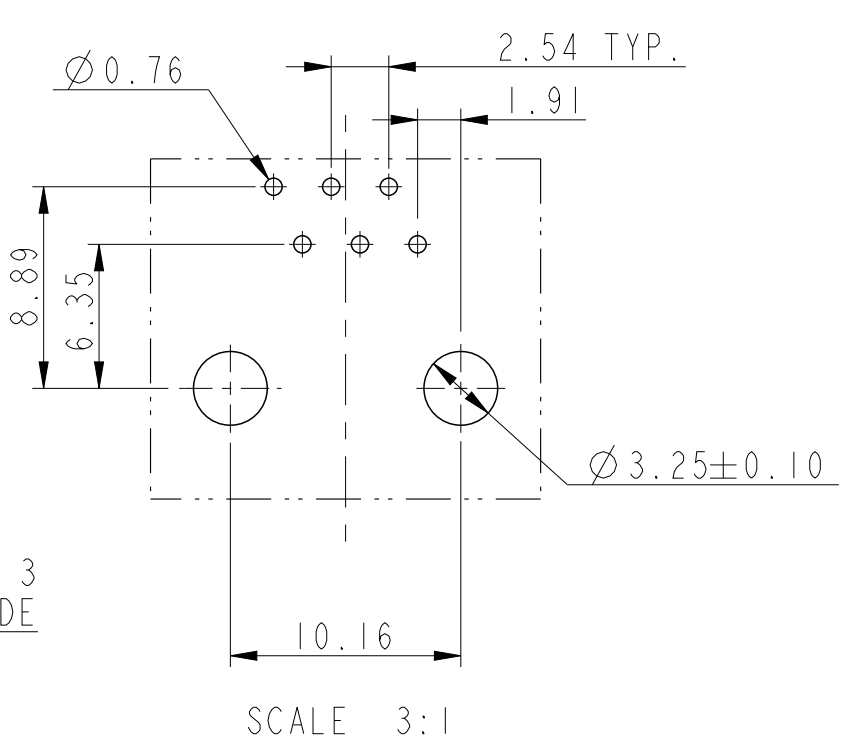
Contact: Ø0.46mm Copper Alloy

Plating:
 Active zone: Gold over nickel on contact area
 Termination zone : SnPb over Nickel (Leaded version)
 : Matte Tin over nickel (Lead Free version)

WIRE POSITION NO.

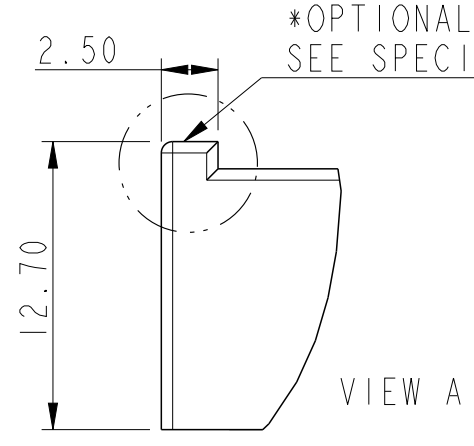


P.C.B. HOLE PATTERN VIEWED FROM TOP



SCALE 3:1

*OPTIONAL-NOTE 3
 SEE SPECIAL CODE



VIEW A

NOTES:

- CONTACT WIRE SHOULD NOT TO BE EXPOSED IN THE WELD AREA. AND WELD FLASH NOT TO EXCEED 0.30 ABOVE [A]
- ALL WIRES MUST BE CONTAINED IN THE SHELF.
- OPTIONAL PROJECTION ADDED TO INCREASE OVERALL HEIGHT OF CONNECTOR. SEE ORDERING INFORMATION.

- LF Products meet European Union Directives and other country Regulations as described in GS-22-008.
- The Housing will withstand exposure to 260° peak temperature for 5 sec in a wave solder application with a 1.6mm Min thick circuit board. Slight deformation of snap pegs may occur at 260-265°C which will not affect the function of the product.
- Lead Free or ROHS Directive labelling to be provided as per GS-14-920 for Lead Free version.

www.fciconnect.com		surface	tolerance std	projection	mm
		ISO 1302	ISO 406 ISO 1101	⊕	↔
TOLERANCES UNLESS OTHERWISE SPECIFIED					
Dr	NEBU P.M	2008-05-19	ANGULAR	0.X	±0.3
Eng	NEBU P.M	2008-05-19	LINEAR	0.XX	±0.15
Chr	NEBU PM	2009-08-19	0° ±2°	0.XXX	±0.05
Appr	SUDHIR V	2009-08-19	Product family MODJACK		ECN 109-0169
6 POL HOUSING			C-BMJ-0082		Rev. G
TELEJACK			CUSTOMER COPY		sheet 1 of 1
catalog no					

rev	ecn no	dr	date
E	108-0023	HVN	2008-05-19
F	108-0081	NG	2008-07-02
G	109-0169	NPM	2009-08-19
-	-	-	-
-	-	-	-
-	-	-	-
-	-	-	-